SPECIFICATIONS

Seven segment Display数码管产品规格书

TOPLITE

MODEL: TOP-CC-3191AH

上海鼎晖科技股份有限公司

SHANGHAI TOPLITE TECHNOLOGY CO., LTD.

www.ledtoplight.com.cn www.ledtoplite.com



TECHNICAL DATA SHEET TOP-CC-3191AH FOR 0.39 inch (9.9mm) digit heigh

 $1 \, / \, 6$

1. PRODUCT INTRODUCTION

- * Low power requirement,
- X Solid state reliability.
- [∗] Wide viewing angle.
- [∗] Easy mounting on P.C. boards.
- **※** RHOS compliant.

2. FEATURES

XTOP-CC-3191AH is a 0.39 inch (9.9mm) digit heigh

% This device is made with white dots and black surface.

3. APPLICATION

- X Digital readout display.
- [∗] *※* Instrument panels.
- [∗] Elevator.

PART NO.	SIZE	CHIP EMITTED COLOR	FACE COLOR
TOPLIGHT-CC-3191AH	0.39 inch (9.9mm) digit height.	Red	Black



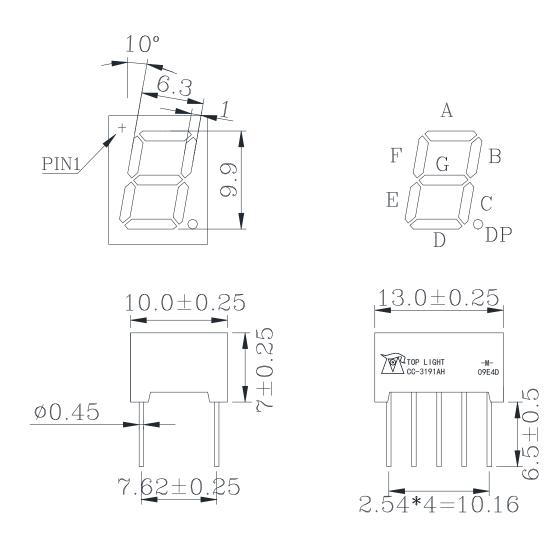
上海鼎晖科技股份有限公司

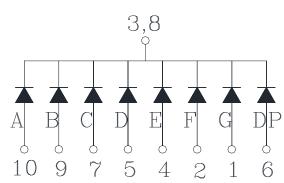
SHANGHAI TOPLITE TECHNOLOGY CO.,LTD. Http://www.ledtoplight.com.cn www.ledtoplite.com

TECHNICAL DATA SHEETTOP-CC-3191AHFOR0.39 inch (9.9mm) digit heigh

2/6

4. PACKAGE DIMENSIONS & CIRCUIT DIAGRAM







TECHNICAL DATA SHEET TOP-CC-3191AH FOR **0.39 inch (9.9mm) digit heigh**

3/6

5. ELECTRICAL/OPTICAL CHARACTERISTIC

5-1. ABSOLUTE MAXIMUM RATINGS (Ta=25°C)

PARAMETER	SYMBOL	VALUE	UNIT
Reverse Voltage	V _R	5	V/seg
Forward Current	$I_{\rm F}$	30	mA/seg
Peak Forward Current (1/10 Duty Cycle)	I _{PEAK}	120	mA/seg
Power Dissipation	P _D	80	mW/seg
Operating Temperature Range	T _A	- 25 ~ + 85	°C
Storage Temperature Range	T _{STG}	- 30 ~ + 85	°C
Solder Temperature	Tsol	260/3	°C/s

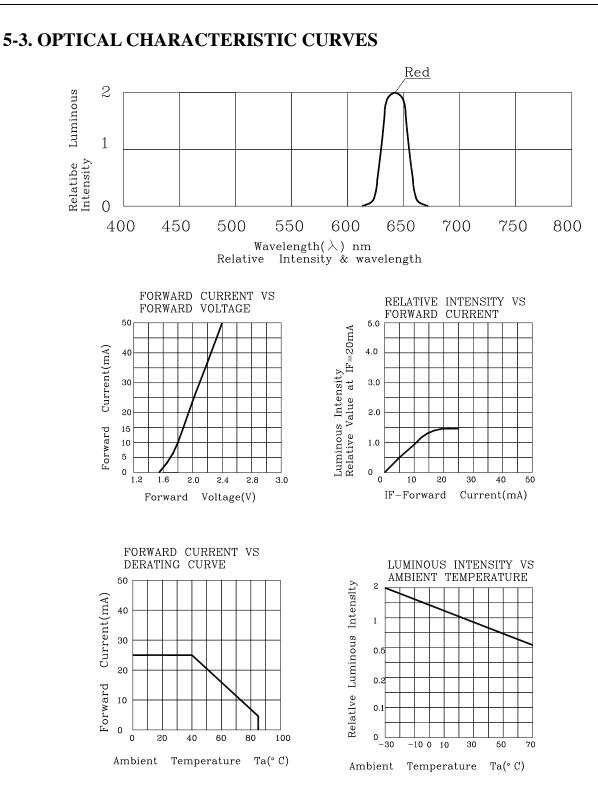
5-2. ELECTRICAL-OPTICAL CHARACTERISTICS (Ta=25°C)

PARAMETER	SYMBOL		MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Luminous Intensity	I _V	K	4726	5435	6144	ucd	I _F =10mA
		М	6145	7066	7987		
		N	7988	9185	10383		
Forward Voltage	V _F		1.70	1.85	2.20	v/seg	I _F =20mA
Chromatographer	λ _p		-	640	-	nm	I _F =20mA
Spectral Line Half-Width	Δλ		-	20	-	nm	I _F =20mA
Reverse Current	I _R		-	-	20	uA	V _R =5v



TECHNICAL DATA SHEET TOP-CC-3191AH FOR 0.39 inch (9.9mm) digit heigh

4/6





TECHNICAL DATA SHEETTOP-CC-3191AHFOR0.39 inch (9.9mm) digit heigh

5/6

6. QUALITY CONTROL AND ASSURANCE

CLASSIFICATION	TEST ITEM	TEST CONDITION		
ENDUTRANCE TEST	OPERATION LIFE	Ta=under room temperature If=12mA-25mA per segment or Ip=80mA/duty=1/8,Pw=1.25mS Ip=160mA/duty=1/16,Pw=1.mS(DOT) Test time=1000HRS(-24HRS+72HRS)		
	MOISTURE	Ta= $65^{\circ}C \pm 5^{\circ}C$ RH=90-95% Test time=240HRS±2HRS		
	HIGH TEMPERATURE HIGH HUMIDITY REVERSE BIAS	Ta=65°C±5°C RH=90-95% VR=5V Test time=500hrs(-24HRS+48HRS)		
	HIGH TEMPERATURE STORAGE	To evaluate device's durability for long term storage in high temperature Ta=85°C±5°C Test time=1000HRS(-24HRS+72HRS)		
	LOW TEMPERATURE STORAGE	Ta=-35 °C \pm 5 °C Test time=1000HRS(-24HRS+72HRS)		
ENVIRONMENTAL TEST	TEMPERATURE CYCLING	Ta=85°C \sim 25°C \sim -35°C time=30min 5min 30min 5min Cycle test:10cycles		
	THERMAL SHOCK	Ta=85°C±5°C~-35°C±5°C time=10min 10min Cycle test:10cycles		
	SOLOER RESISTANCE	T.sol=260°C±5°C time=10±1sec		
	SOLOER ABILITY	T.sol=230°C±5°C time=5±1sec		



TECHNICAL DATA SHEET TOP-CC-3191AH FOR **0.39 inch (9.9mm) digit heigh**

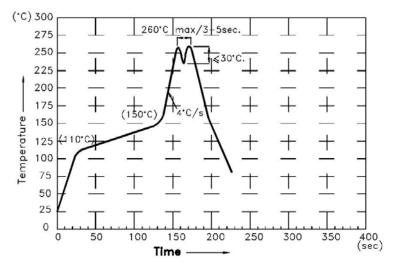
6/6

7. SOLDERING CONDITIONS

The recommended conditions for soldering are as follows.

Because the component is made with epoxy resin, the units are susceptible to heat. Therefore, the preheating and soldering temperatures should be kept as low as possible to avoid damage.

- 7-1. Manual Soldering Conditions(with 1.5mm Iron tip). Iron Tip Temperature: 350°C Max, Time: 3s Max. Position: The iron should be situated at least 2mm away from the root of the leads.
- 7-2. Through the Wave Soldering Conditions Wave Soldering Profile For Lead-free Through-hole LED.



- **7-3.** Soldering General Notes:
 - a. Recommend manual soldering to be used only for repair and rework purposes. The soldering iron should not exceed 30W in power. The tip of the soldering iron should not touch the reflector case to avoid heat-damage.
 - b. Maintain the pre-heat and peak temperatures with dip units as low as possible and the times as short as is feasible, since the products are susceptible to heat during flow soldering.
 - c. After soldering, least three minutes for the component to cool to room temperature before further operations.
 - d. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with toplight for compatibility.